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PRITCHARD et al.(10) **Pub. No.: US 2022/0369452 A1**(43) **Pub. Date: Nov. 17, 2022**(54) **SLOTTED VIAS FOR CIRCUIT BOARDS****Publication Classification**(71) Applicant: **Dell Products L.P.**, Round Rock, TX
(US)(51) **Int. Cl.**
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(US)(57) **ABSTRACT**(21) Appl. No.: **17/319,577**

A circuit board may include a traditional via electrically coupled to a first layer of the circuit board and coupled to a second layer of the circuit board and a slotted via formed within the circuit board proximate to the traditional via, the slotted via comprising an opening through a first surface and a second surface of the circuit board and a layer of conductive material formed on interior walls of the opening.

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